



PATENT

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Sir:

The patent application of

Inventor(s): ABE ET AL

For: THERMOSETTING SOLDERING FLUX AND SOLDERING
PROCESS

is attached for filing.

- [X] This application claims the priority of Japanese Patent Application
No. 344979/1999 filed on December 3, 1999.
- [X] This application is being filed in Japanese.
- [X] This application is being filed without a declaration or fee.

Respectfully submitted,

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